



SOT338-1

plastic shrink small outline package; 16 leads; body width 5.3 mm

8 February 2016

Package information

1. Package summary

Terminal position code	D (double)
Package type descriptive code	SSOP16
Package type industry code	SSOP16
Package style descriptive code	SSOP (shrink small outline package)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
JEDEC package outline code	MO-150
Mounting method type	S (surface mount)
Issue date	19-2-2003

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	6	-	6.2	6.4	mm
E	package width	5.2	-	5.3	5.4	mm
A	seated height	[tbd]	-	2	2	mm
A ₂	package height	1.65	-	1.75	1.8	mm
n ₂	actual quantity of termination	-	-	16	-	



2. Package outline

SSOP16: plastic shrink small outline package; 16 leads; body width 5.3 mm

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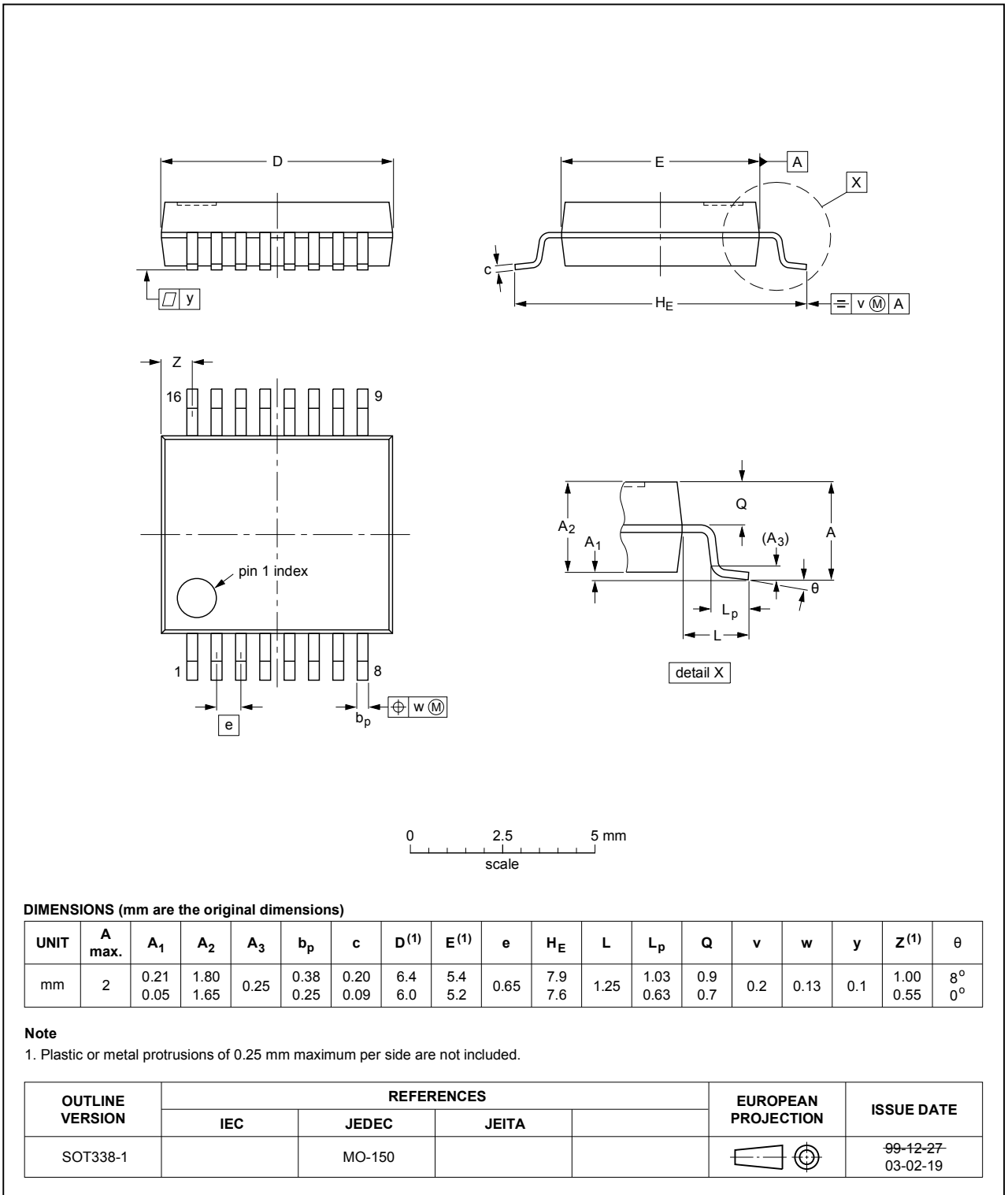
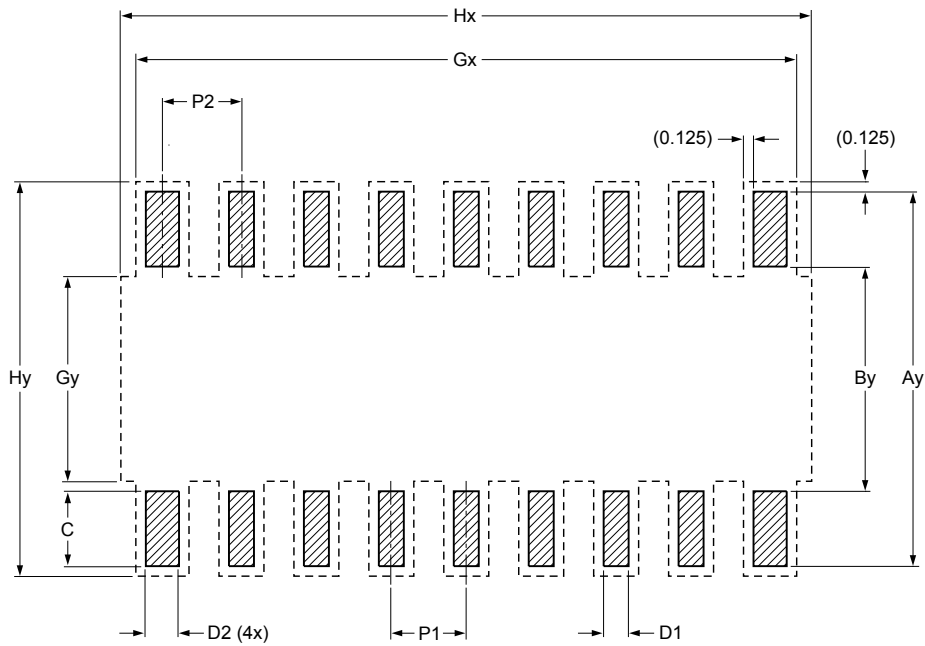


Fig. 1. Package outline SSOP16 (SOT338-1)


3. Soldering

Footprint information for reflow soldering of SSOP16 package

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Generic footprint pattern
Refer to the package outline drawing for actual layout

 solder land
 - - - - occupied area

DIMENSIONS in mm

P1	P2	Ay	By	C	D1	D2	Gx	Gy	Hx	Hy
0.65	0.75	8.6	5.4	1.6	0.4	0.6	5.6	6.1	7.0	8.85

Issue date ~~09-02-22~~
15-03-26

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Fig. 2. Reflow soldering footprint for SSOP16 (SOT338-1)

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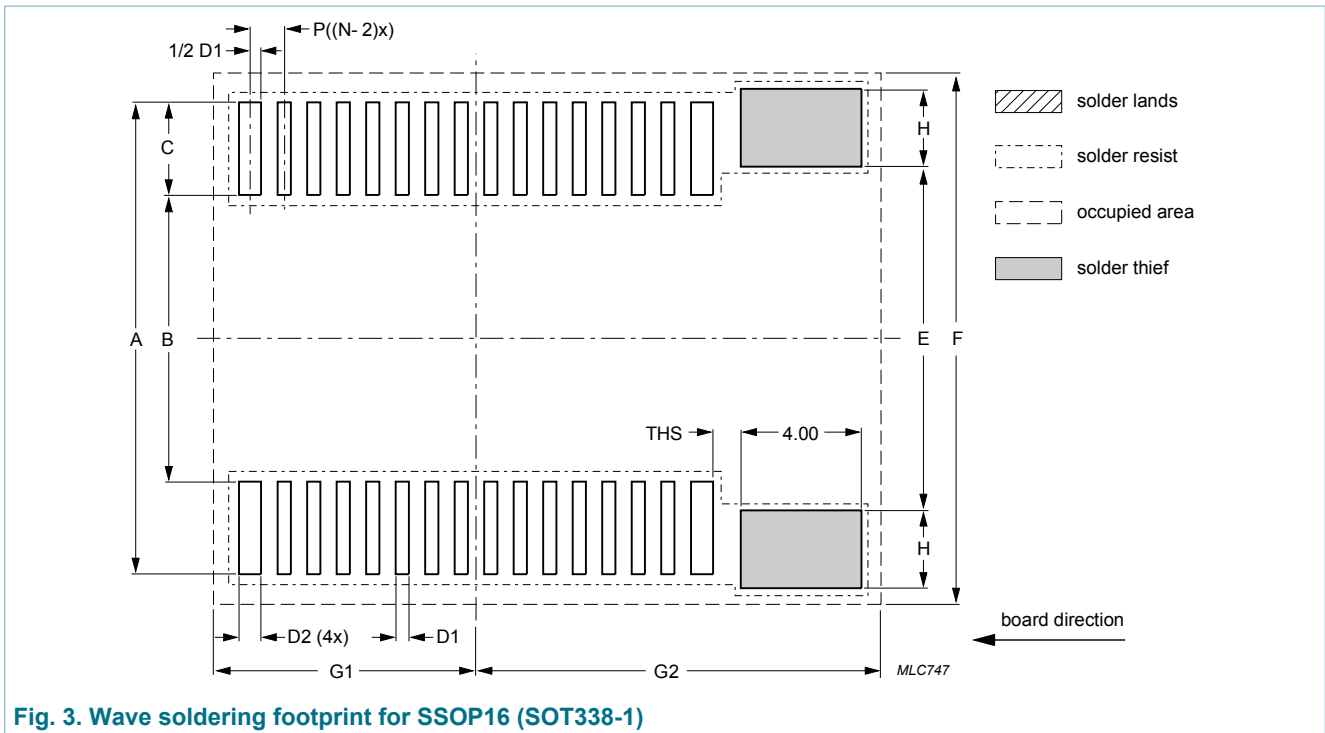


Fig. 3. Wave soldering footprint for SSOP16 (SOT338-1)

4. Legal information

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